EPO-TEK® EV2118-2

Epoxy; Epoxide

Epoxy Technology Inc.

Message:

A silver-filled, electrically conductive epoxy designed for semiconductor and electronic assembly. Formerly 78-118-2

General Information			
Filler / Reinforcement	Silver		
Features	Electrically Conductive		
Uses	Adhesives		
	Electrical/Electronic Applications		
Agency Ratings	EC 1907/2006 (REACH)		
	EU 2003/11/EC		
	EU 2006/122/EC		
RoHS Compliance	RoHS Compliant		
Forms	Paste		
Physical	Nominal Value	Unit	
Particle Size	20.0	μm	
Degradation Temperature	325	°C	
Operating Temperature			
Continuous	-55 to 150	°C	
Intermittent	-55 to 250	°C	
Storage Modulus	4.73	GPa	
Thixotropic Index	4.40		
Weight Loss on Heating			
200°C	0.61	%	
250°C	0.84	%	
300°C	1.6	%	
Thermal	Nominal Value	Unit	
Glass Transition Temperature	40.0	°C	
Thermal Conductivity	4.0	W/m/K	
Thermoset	Nominal Value	Unit	
Thermoset Components			
Part A	Mix Ratio by Weight: 1.0		
Part B	Mix Ratio by Weight: 1.0		
Shelf Life (23°C)	52	wk	
Uncured Properties	Nominal Value	Unit	

Color		
1	Silver	
2	Silver	
Density		
Part A	2.52	g/cm³
Part B	3.32	g/cm³
Viscosity ³ (23°C)	2.8	Pa·s
Curing Time (150°C)	0.17	hr
Pot Life	4300	min
Cured Properties	Nominal Value	Unit
Shore Hardness (Shore A)	55	
Volume Resistivity (23°C)	< 5.0E-4	ohms·cm
NOTE		
1.	Part B	
2.	Part A	
3.	100 rpm	

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